

HEAT SINK ASSEMBLY

ABSTRACT OF THE DISCLOSURE

A heat sink assembly for use in an electrical apparatus having a printed circuit board having an electromagnetic device is disclosed. The heat sink assembly comprises a first heat-dissipating piece disposed between the electromagnetic device and the printed circuit board for transferring the heat generated from the electromagnetic device away the printed circuit board, and a second heat-dissipating piece disposed on the edge of the printed circuit board and contacting with the first heat-dissipating piece for transferring the heat from the first heat-dissipating piece away the printed circuit board.